

DA 120 Die Attach Product Datasheet

High Reliability
Excellent Flexibility
Excellent Adhesion

Description

DA 120 is a die/lid attach adhesive offering a low modulus and low glass transition temperature. It has a low viscosity and is easy to apply. DA 120 offers excellent adhesion, thermal shock, and thermal resistance performance.

Typical Physical Properties

Product Name	DA 120 Lid Attach Adhesive
PROPERTIES OF UNCURED MATERIAL	
Appearance	yellowish
Resin Type	Epoxy
Specific Gravity (ASTM D 1475-60)	1.1 – 1.2 g/cc
Viscosity	5000-8000 cp
PROPERTIES OF CURED MATERIAL	
Glass Transition Temperature (T _g) (ASTM D3418-82)	-35 °C
Tensile Strength (MPa)	6-8
C.T. E (ASTM E 831), PPM /°C (ASTM E 831)	65

Young's modulus (MPa)	0.1-3
Extractable ions (MIL-STD-883E)	
Na+	<5ppm
K+	<5ppm
F-	<5ppm
Cl-	<10ppm

Recommended Curing Conditions

1-2 hours at 120°C

Storage & Shelf Life

6 months provided materials are kept in a sealed original container at – 40°C. Storage beyond this period can produce higher viscosity. Protect from moisture, evaporation and foreign materials. Process ability of these products can be adversely affected by evaporation and contamination.

Safety

DA 120 is a friendly, non-toxic material. However, general hygiene practice is recommended when handling this material. For detailed information, please consult the product SDS.

Package

DA 120 solder adhesives are available in 10cc and 30cc. Other packages are available depending upon customer's request. Contact YINCAE for order information.